

Title (en)
WAFER DELIVERY SYSTEM

Title (de)
VERABREICHUNGSSYSTEM AUF DER BASIS VON OBLADEN

Title (fr)
SYSTEME D'APPORT PAR CACHET

Publication
EP 1162988 A1 20011219 (EN)

Application
EP 00917953 A 20000316

Priority
• US 0006772 W 20000316
• US 27082099 A 19990318

Abstract (en)
[origin: WO0054794A1] A primarily grain-based, or other non-sugar carbohydrate-based, wafer (typically disc-shaped and having a diameter of between about 7/8 inch-1 1/2 inch (e.g. about 2.1-3.8 cm) and a thickness of between about 1-2 mm (e.g. about 1/16 inch)) is used as a delivery system for a medicinal treatment or food supplement, preferably a homeopathic remedy, Chinese herb, or a combination of homeopathic medicines and Chinese herbs, with or without other substances. A dry substance comprising the Chinese herb, homeopathic remedy, or mixture of them is mixed with a solvent to produce a mother tincture, the tincture is preferably attenuated, and then the wafer is impregnated with the attenuation, as by soaking the wafer in the solvent containing the dry substance, or spraying the solvent containing the dry substance on the wafer, or incorporating the attenuation in the wafer during wafer production. Then solvent is evaporated, and the wafer is packaged for transport to a patient in need of the treatment or food supplement provided by the attenuation.

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A61K 35/78; **A61K 9/00**; **A61P 43/00**

IPC 8 full level
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Citation (search report)
See references of WO 0054794A1

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